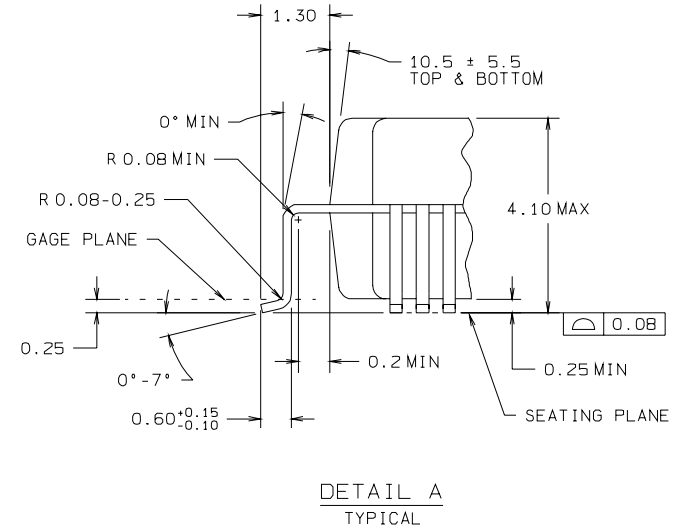
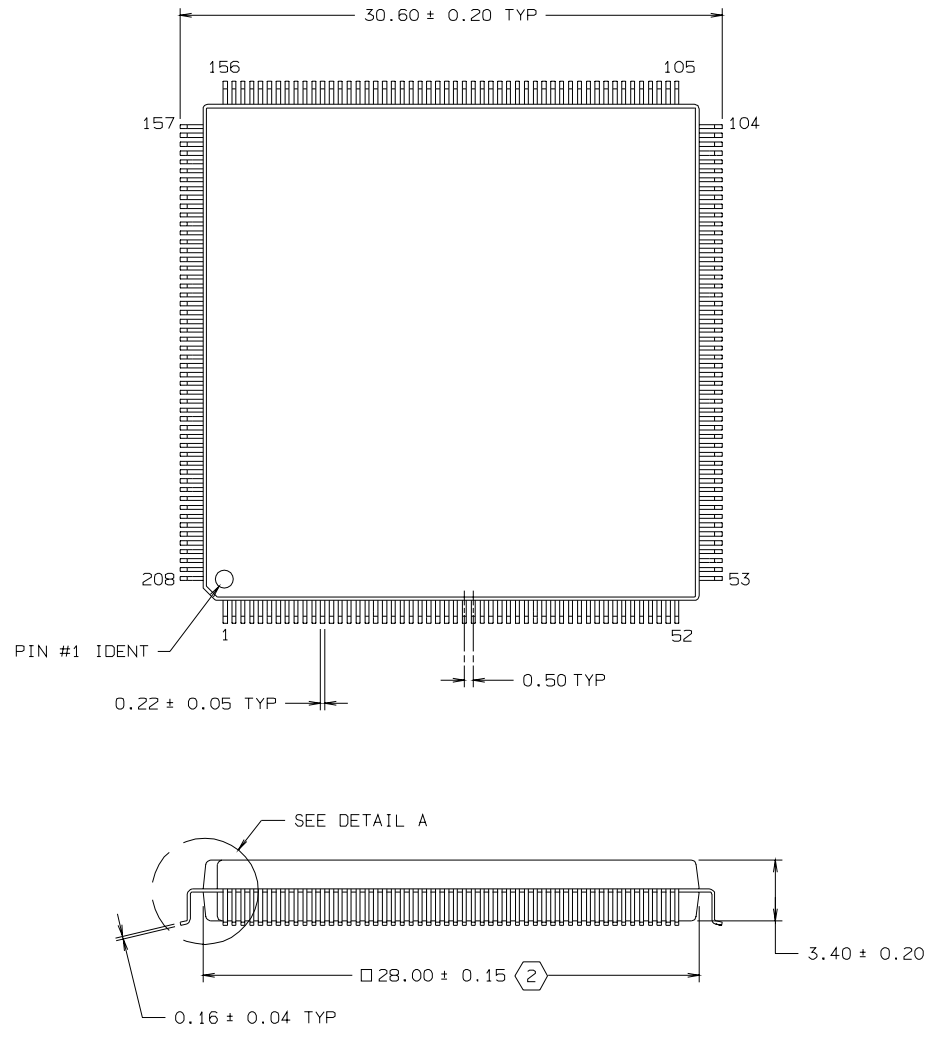


R E V I S I O N S				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	09265	08/25/92	TL/HJK
B	REVISE TITLE, NOTE 3 & DETAIL A: LEAD WIDTH WAS 0.23	09960	09/09/93	TL/



NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
5.08 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON FRAME.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- REFERENCE JEDEC REGISTRATION MO-143, VARIATION FA-1, DATED 3/93.

DIMENSIONS ARE IN MILLIMETERS				
APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN T. LEQUANG	08/25/92	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DFTG. CHK.		PQFP, JEDEC METRIC, (S), 28 X 28 X 3.4 mm, 208 LEAD		
ENGR. CHK.				
APPROVAL				
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	N/A	C	MKT-VUW208A	B
DO NOT SCALE DRAWING		SHEET 1 OF 1		